

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
60V	32mΩ@10V	5A
	38mΩ@4.5V	

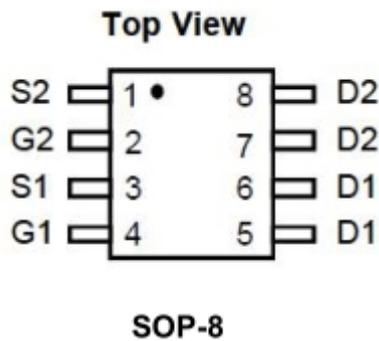
Feature

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high EAS
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

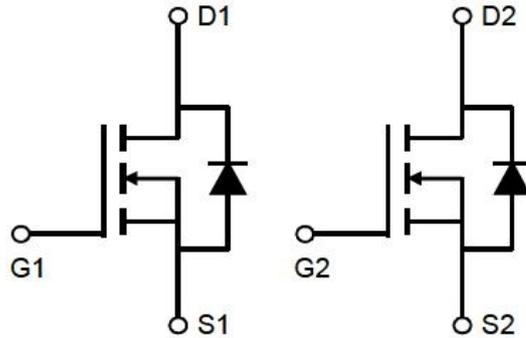
Applications

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

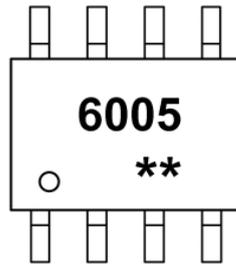
Package



Circuit diagram



Marking



6005 =Device Code
 ** =Week Code

Absolute maximum ratings

($T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	5	A
Pulsed Drain Current	I_{DM}	20	A
Power Dissipation	P_D	2	W
Thermal Resistance from Junction to Ambient ²⁾	$R_{\theta JA}$	62.5	$^{\circ}\text{C}/\text{W}$
Junction Temperature	T_J	150	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	-55 ~ +150	$^{\circ}\text{C}$

Electrical characteristics

($T_A=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	$BV_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	60			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 60V, V_{GS} = 0V$			1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	μA
Gate threshold voltage ⁽¹⁾	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.5	2.5	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 5A$		32	42	m Ω
		$V_{GS} = 4.5V, I_D = 3A$		38	50	
Forward Transconductance	g_{FS}	$V_{DS} = 5V, I_D = 5A$	11			S
Dynamic Characteristics⁴⁾						
Input Capacitance	C_{iss}	$V_{DS} = 30V, V_{GS} = 0V,$ $f = 1MHz$		590		pF
Output Capacitance	C_{oss}			60		
Reverse Transfer Capacitance	C_{rss}			25		
Switching Characteristics⁴⁾						
Turn-on Delay Time	$T_{d(on)}$	$V_{DD} = 30V, I_D = 2A,$ $V_{GS} = 10V, R_G = 3\Omega,$ $R_L = 6.7\Omega$		5		nS
Turn-on Rise Time	T_r			2.6		
Turn-Off Delay Time	$T_{d(off)}$			16.1		
Turn-Off Fall Time	t_f			2.3		
Total Gate Charge	Q_g	$V_{DS} = 30V, I_D = 4.5A,$ $V_{GS} = 10V$		14		nC
Gate-Source Charge	Q_{gs}			2.9		
Gate-Drain Charge	Q_{gd}			5.2		
Source-Drain Diode Characteristics						
Diode Forward Voltage	V_{SD}	$I_S = 20A, V_{GS} = 0V$			1.2	V

Notes:

1. Repetitive rating: Pulse width limited by junction temperature.
2. Surface mounted on FR4 board, $t \leq 10s$.
3. Pulse Test: Pulse Width $\leq 80\mu s$, Duty Cycle $\leq 0.5\%$.
4. Guaranteed by design, not subject to producing.

Typical Characteristics

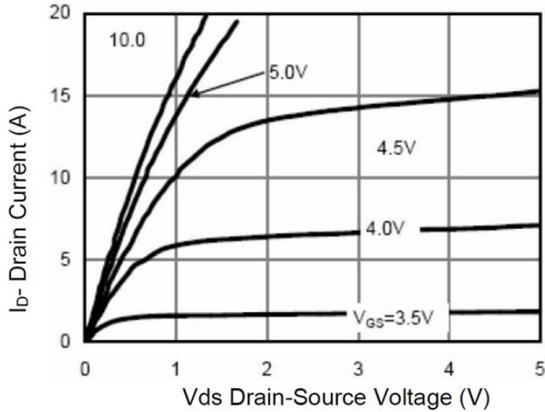


Figure 1 Output Characteristics

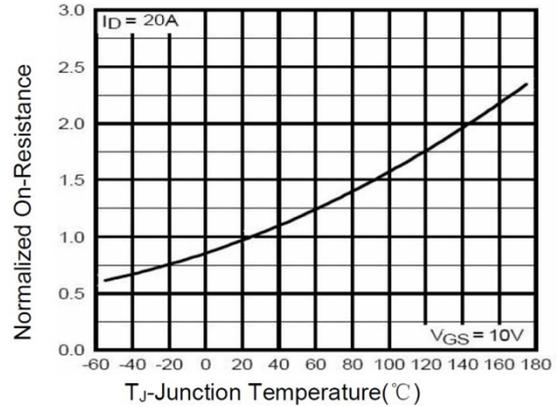


Figure 4 Rdson-Junction Temperature

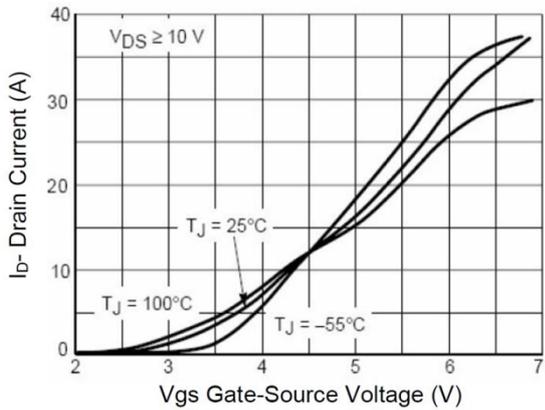


Figure 2 Transfer Characteristics

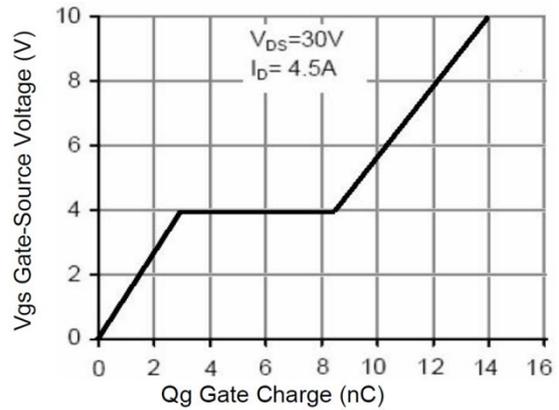


Figure 5 Gate Charge

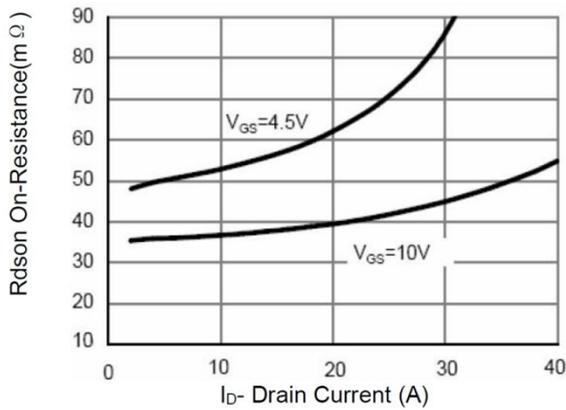


Figure 3 Rdson- Drain Current

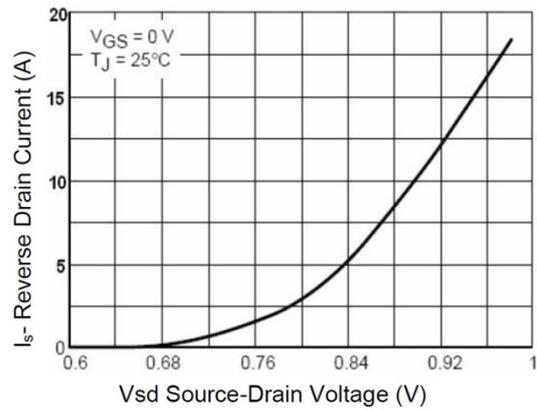


Figure 6 Source- Drain Diode Forward

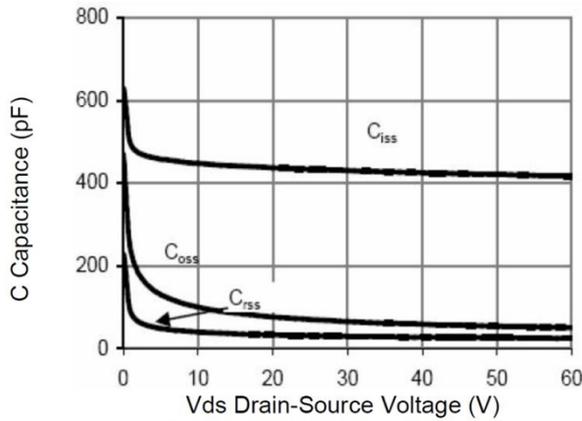


Figure 7 Capacitance vs Vds

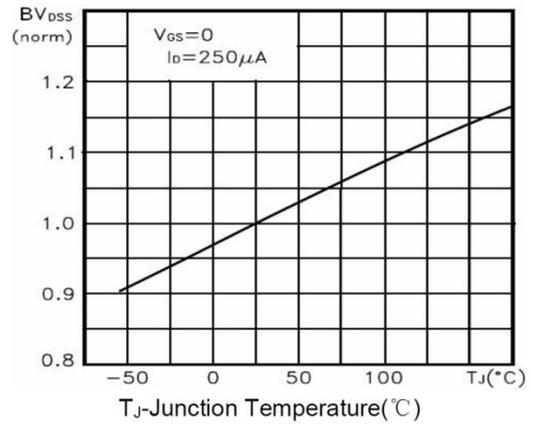


Figure 9 BV_{DSS} vs Junction Temperature

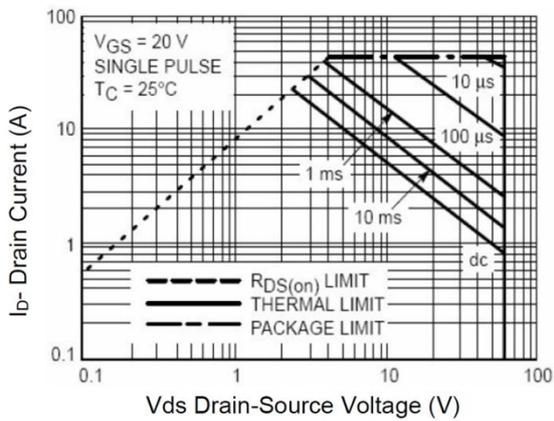


Figure 8 Safe Operation Area

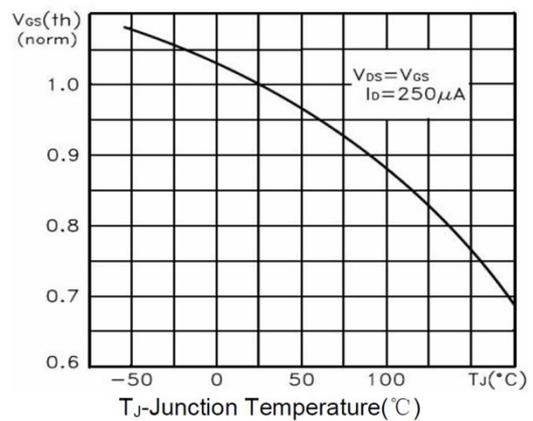


Figure 10 $V_{GS(th)}$ vs Junction Temperature

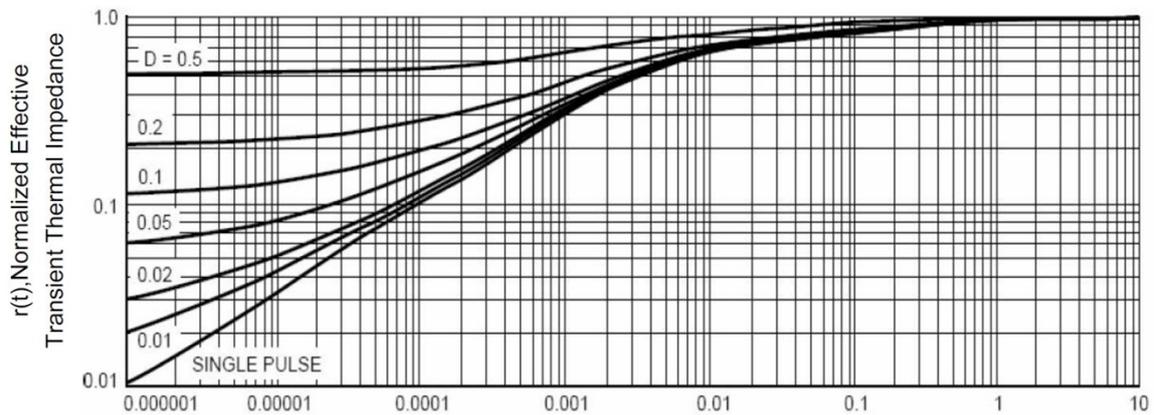
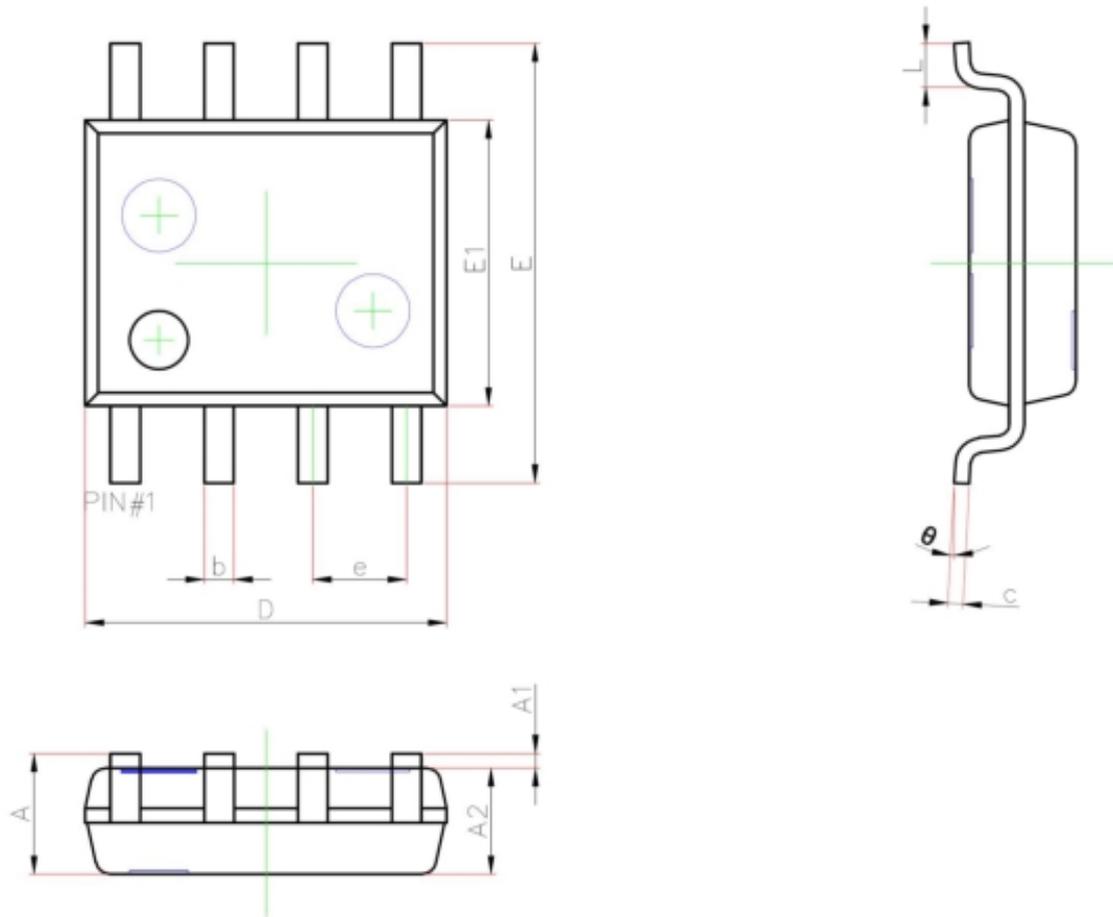


Figure 11 Normalized Maximum Transient Thermal Impedance

SOT-8 Package Information



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.35	1.75
A1	0.10	0.25
A2	1.35	1.55
b	0.33	0.51
c	0.17	0.25
D	4.80	5.00
e	1.27 REF.	
E	5.80	6.20
E1	3.80	4.00
L	0.40	1.27
θ	0°	8°